Title (en)

METHOD FOR CONNECTING A CURRENT SUPPLY WIRE WITH A CONTACT PATCH OF AN ELECTRICAL LAMP

Title (de)

VERFAHREN ZUM VERBINDEN EINES STROMZUFÜHRUNGSDRAHTES MIT EINEM KONTAKTBLECH EINER ELEKTRISCHEN LAMPE

Title (fr)

PROCEDE DESTINE A RELIER UN FIL D'ALIMENTATION DE COURANT A UNE PLAQUE DE CONTACT D'UNE LAMPE ELECTRIQUE

Publication

EP 1166331 A1 20020102 (DE)

Application

EP 01909509 A 20010122

Priority

- DE 0100249 W 20010122
- DE 10003434 A 20000127

Abstract (en)

[origin: DE10003434A1] The invention relates to a method for connecting a contact patch (2) of a lamp socket, with a current supply wire (4), fed through an opening (2a) in said contact patch (2). The current supply wire (4) and the contact patch (2) are soldered together, by means of another wire (5) serving as a welding agent, whereby an arc is generated between the additional wire (5) and the current supply wire (4), or the contact patch (2). The solidified melt of the additional wire (5) closes the opening (2a) and forms a reliable soldered connection between the current supply wire (4) and the contact patch (2). The electrical voltage used to generate the arc, is preferably of a polarity such that the additional wire (5) is the anode and the current supply wire (4), or the contact patch (2) is the cathode. Said soldering process is best conducted under a protective atmosphere.

IPC 1-7

H01K 1/46; H01J 5/54

IPC 8 full level

H01J 5/46 (2006.01); **H01J 9/24** (2006.01); **H01J 9/36** (2006.01); **H01J 61/36** (2006.01); **H01K 1/40** (2006.01); **H01K 1/46** (2006.01); **H01K 3/16** (2006.01)

CPC (source: EP KR US)

H01J 5/46 (2013.01 - EP US); **H01J 9/247** (2013.01 - EP US); **H01J 61/36** (2013.01 - EP US); **H01K 1/40** (2013.01 - EP US); **H01K 1/46** (2013.01 - KR); Y10T 29/49162 (2015.01 - EP US); Y10T 29/49174 (2015.01 - EP US)

Designated contracting state (EPC)

BE DE FR GB IT NL

DOCDB simple family (publication)

US 2003070293 A1 20030417; **US 6759618 B2 20040706**; CA 2368761 A1 20010802; DE 10003434 A1 20010802; DE 50109529 D1 20060524; EP 1166331 A1 20020102; EP 1166331 B1 20060419; HU 226839 B1 20091228; HU P0200885 A2 20020629; JP 2003521097 A 20030708; JP 4767469 B2 20110907; KR 100723074 B1 20070529; KR 20020001794 A 20020109; MX PA01009765 A 20030624; WO 0156061 A1 20010802

DOCDB simple family (application)

US 93750301 A 20010927; CA 2368761 A 20010122; DE 0100249 W 20010122; DE 10003434 A 20000127; DE 50109529 T 20010122; EP 01909509 A 20010122; HU P0200885 A 20010122; JP 2001555118 A 20010122; KR 20017012044 A 20010921; MX PA01009765 A 20010122